



ENVIRONMENTAL AND PACKAGE TESTING DATA FOR PowerPAK® ChipFET®					
STRESS	SAMPLE SIZE	DEVICE HR./CYC	CONDITION	TOTAL FAILS	FAIL PERCENTAGE
BOND INT	120	60 000	200 °C + N2	0	0
HAST	1024	102 400	130 °C, 85 % RH	0	0
Power Cycle	82	1 230 000	DELTA T _j = 100 °C	0	0
Pressure Pot	1292	124 032	121°, 15 PSIG	0	0
Solder DUNK	245	735	260 °C, 10 s	0	0
Solderability	30	240	883 M2003	0	0
Temp. Cycle	2838	1 696 800	-55 °C to 150 °C	0	0